

1FW

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Chuen Rong Leu et al.  
Assignee: Bridge Semiconductor Corporation  
Title: METHOD OF MAKING A SEMICONDUCTOR CHIP  
ASSEMBLY WITH AN EMBEDDED METAL PILLAR  
Serial No.: 10/719,823 Filed: November 21, 2003  
Examiner: Unknown Group Art Unit: 2812  
Atty. Docket No.: BDG024-1

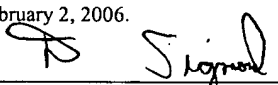
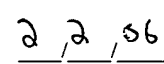
---

COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313

**TRANSMITTAL OF FORMAL DRAWINGS**

In response to the Notice of Non-Compliant Amendment dated January 30, 2006, formal drawings (36 sheets) are attached with "Replacement Sheet" labeled in the top margin.

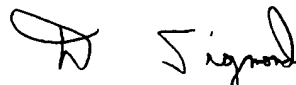
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on February 2, 2006.

David M. Sigmond  
Attorney for Applicant

2/2/06  
Date of Signature

Respectfully submitted,



David M. Sigmond  
Attorney for Applicant  
Reg. No. 34,013  
(303) 554-8371  
(303) 554-8667 (fax)